

Product Change Notification - JAON-24EPKL576

Date:

08 Nov 2019

Product Category:

Access Networks; Line Drivers; Broadband Gateway; Network Synchronization; Clock Synthesis; Voice Audio; Jitter Attenuators; Clock and Timing - Clock Generation; Clock and Timing - Clock and Data Distribution; Others

Affected CPNs:



Notification subject:

CCB 3970 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in various packages at ASEM assembly site.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in various packages at ASEM assembly site.

Pre Change:

Assembled at ASEM assembly site using palladium coated copper (PdCu) or Copper (Cu) bond wire.

Post Change:

Assembled at ASEM assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Group -Malaysia (ASEM)	ASE Group -Malaysia (ASEM)	
Wire material			
Die attach material	See attached pre and post change per affected package typ		
Molding compound material			
Lead frame material			

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond



wire material.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 1, 2020 (date code: 2010)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and

post change parts

Time Table Summary:

		November 2019			->		Ма	rch 20	020		
Workweek	44	45	46	47	48	,	10	11	12	13	14
Qual Report Availability		X									
Final PCN Issue Date		X									
Estimated Implementation											
Date							^				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN # Qual Report.

Revision History:

November 8, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on March 1, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-24EPKL576_Qual_Report.pdf PCN_JAON-24EPKL576_Pre and Post Change Summary.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Pre and Post Change 16L VQFN package (3x3x1mm)

	Pre Change	Post Change
Assembly Site Location	ASE Group -Malaysia (ASEM)	ASE Group -Malaysia (ASEM)
Wire material	PdCu	CuPdAu
Die attach material	HR5104	HR5104
Molding compound material	CEL-9240HF10AK-G1	CEL-9240HF10AK-G1
Lead frame material	C194	C194



Pre and Post Change 164L VQFN package (13x13x0.95mm)

	Pre Change	Post Change
Assembly Site Location	ASE Group -Malaysia (ASEM)	ASE Group -Malaysia (ASEM)
Wire material	PdCu	CuPdAu
Die attach material	1076DS	1076DS
Molding compound material	G631H-Y	G631H-Y
Lead frame material	C7025	C7025



Pre and Post Change VQFN package (Other than specified above)

	Pre Change	Post Change
Assembly Site Location	ASE Group -Malaysia (ASEM)	ASE Group -Malaysia (ASEM)
Wire material	PdCu	CuPdAu
Die attach material	1076DS	1076DS
Molding compound material	CEL-9240HF10AK-G1	CEL-9240HF10AK-G1
Lead frame material	C194	C194

This is applicable to below package types, lead counts and package dimension:

Lead Count	Package Type	Package Dimension
16L	VQFN	4x4x1mm
24L	VQFN	4x4x1mm
28L	VQFN	4x5x1mm
48L	VQFN	7x7x1mm
32L	VQFN	8x8xmm
32L	VQFN	5x5x1mm
24L	VQFN	6x6x1mm
64L	VQFN	9x9x1mm
40L	VQFN	6x6x1mm
53L	VQFN	7x7x1mm
56L	VQFN	8x8x1mm
64L	VQFN	9x9x1mm
48L	VQFN	7x7x1mm
53L	VQFN	7x7x1mm
56L	VQFN	8x8x1mm



Pre and Post Change LQFP, MQFP and TQFP packages

	Pre Change	Post Change
Assembly Site Location	ASE Group -Malaysia (ASEM)	ASE Group -Malaysia (ASEM)
Wire material	Cu or PdCu	CuPdAu
Die attach material	Yiz8143	Yiz8143
Molding compound material	CEL-9240HF10AK-G1	CEL-9240HF10AK-G1
Lead frame material	C7025	C7025

This is applicable to below package types, lead counts and package dimension:

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Lead Count	Package Type	Package Dimension	
64L	LQFP	14x14x1.4mm	
176L	LQFP	20x20x1.4mm	
80L	LQFP	12x12x1.4mm	
44L	LQFP	10x10x1.4mm	
80L	LQFP	14x14x1.4mm	
48L	LQFP	7x7x1.4mm	
64L	LQFP	10x10x1.4mm	
100L	LQFP	14x14x1.4mm	
100L	MQFP	14x20x2.72mm	
44L	TQFP	10x10x1mm	
128L	TQFP	14x14x1mm	
64L	TQFP	10x10x1mm	
48L	TQFP	7x7x1mm	
32L	TQFP	7x7x1mm	



Pre and Post Change BGA packages

	Pre Change	Post Change
Assembly Site Location	ASE Group -Malaysia (ASEM)	ASE Group -Malaysia (ASEM)
Wire material	PdCu	CuPdAu
Die attach material	AB2100A	AB2100A
Molding compound material	G750E	G750E
Substrate material	830/832NX	830/832NX

This is applicable to below package types, lead counts and package dimension:

Lead Count	Package Type	Package Dimension
144L	BGA	13x13x1.95mm
64L	LBGA	9x9x1.72mm
100L	LBGA	11x11x1.55mm
196L	LBGA	15x15x1.65mm
100L	LFBGA	9x9x1.72mm
256L	HBGA	17x17x1.97mm
96L	VFBGA	7x7mm



QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: JAON-24EPKL576

Date: Oct 18, 2019

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in various packages at ASEM assembly site.



Purpose

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in

various packages at ASEM assembly site.

QUAL ID CCB#3970

CCB No.: 3970

Package Qualification Information

Package	44L PLCC	80L LQFP	48L VQFN	100L LBGA
Lead frame material	C194	C7025	C194	830/832NX
Epoxy / Die Attach material	YIZ8143	YIZ8143	1076DS	2100A
Bond wire material	CuPdAu	CuPdAu	CuPdAu	CuPdAu
Mold compound material	CEL 9240HF10AK-G1	CEL 9240HF10AK-G1	CEL 9240HF10AK-G1	G750E
Plating	100% Sn	100% Sn	100% Sn	SAC305



Manufacturing Information

Assembly Lot No.	Part No.	Package
Assembly Lot No.	Tartito.	Fackage
904LE98B01	MT8816	PLCC44
904LE97B01	Le88266	LQFP80 14X14
903LE93B01	Le9641	QFN48 7X7
903LE92B01	ZL80018	LBGA100 11X11

Result	Y	Dace	Fail	
Result	Λ	Pass	Fail	

All four qual packages pass reliability test per Qual plan. These packages were qualified per the Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

	PACKAGE QUALIFICA	ATION	REPO	ORT		
Test Number (Reference)	Test Condition	Standard / Method	Qty. (Acc.)	Def/S S	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	85°C/ 85%RH Moisture Soak 168 hrs. System: 3x Convection-Reflow 265°C max (IPC/JEDEC J-STD-020E)	IPC/JEDE C J-STD- 020E	1015	0/1015	Pass	

Precondition Prior Perform	Electrical Test:+25°C and 85°C	JESD22- A113	635	0/1015		Good Devices
Reliability Tests (At MSL Level 3)	Bake 150°C, 24 hrs System:			0/1015		
	85°C/85%RH Moisture Soak 168 hrs. System:			0/1015		
	3x Convection-Reflow 265°C max			0/1015		
	System:					
	Electrical Test :+25°C and 85°C			0/1015	Pass	

	PACKAGE QU	ALIFICA	ATION	REF	PORT		
Test Number (Reference)	Test Condition		Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: Lead frame package: -65°C to +150°C, 500 Cycles BGA/Substrate package:		JESD22- A104		340	Pass	Parts had been pre-conditioned at 260°C
		Sub		340	0/340	Pass	255 L/F 3 lot 85 Sub 1 lot
UNBIASED-	Stress Condition: +130°C/85%RH, 96 hrs. System:		JESD22- A118		340		Parts had been pre-conditioned at 260°C
HAST	Electrical Test: +25°C System:			340	0/340	Pass	85 units /4 lot
High Temperature	Stress Condition: 150°C, 500 hrs System: N/A	Bake	JESD22- A103		335		Parts had been pre-conditioned at 260°C
Storage Life	Electrical Test:+ 25°C System:			335	0/335	Pass	3 lot/85 L/F 1 lot/80 sub

JAON-24EPKL576 - CCB 3970 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in various packages at ASEM assembly site.

Affected Catalog Part Numbers (CPN)

LE79112AKVCT

LE79114KVC

LE79124KVC

LE79124KVCT

LE79128KVC

LE79128KVCT

LE79234KVC

LE792388TVC

LE792388TVCT

LE792388VQC

LE792388VQCT

LE79252BTC

LE79252BTCT

LE79271AMQC

LE79271AMQCT

LE79271MQC

LE79271MQCT

LE79272PQC

LE79272PQCT

LE79Q2281DVC

LE79Q2281DVCT

LE79Q2284MVC

LE79Q2284MVCT

LE79R70-1FQC

LE87100NQC

LE87100NQCT

LE87251NQC

LE87251NQCT

LE87270NQC

LE87270NQCT

LE87281NQC

LE87281NQCT

LE87285NQC

LE87285NQCT

LE87286NQC

LE87290YQC

LE87290YQCT

LE87401NQC

LE87401NQCT

LE87411NQC

LE87411NQCT

LE87501NQC

LE87501NQCT

LE87502MQC

LE87502MQCT

LE87511NQC

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JAON-24EPKL576 - CCB 3970 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in various packages at ASEM assembly site. LE9530DPQC LE9530DPQCT LE9540CUQC LE9540CUQCT LE9540DUQC LE9540DUQCT LE9541CUQC DS3105LN2 DS3106LN2 LE57D111BTC LE57D111BTCT LE57D121BTC LE57D121BTCT LE57D122BTC LE57D122BTCT LE58QL021BVC LE58QL021BVCT LE58QL022BVC LE58QL022BVCT LE58QL061BVC LE58QL061BVCT LE58QL063HVC LE58QL063HVCT LE79112AKVC LE9541CUQCT LE9541DUQC LE9541DUQCT LE9551CMQC LE9551CMQCT LE9551DMQC LE9551DMQCT LE9622RQC LE9622RQCT LE9632RQC LE9632RQCT LE9641PQC LE9641PQCT LE9642PQC LE9642PQCT LE9651PQC LE9651PQCT LE9652PQC LE9652PQCT LE9661WQC LE9661WQCT LE9662WQC LE9662WQCT LE9672WQC LE9672WQCT

JAON-24EPKL576 - CCB 3970 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in various packages at ASEM assembly site. MAX3674ECM2 MAX3674ECM2T MT8816AF1 MT9074AL1 ZL30100QDG1 ZL30101QDG1 ZL30102QDG1 ZL30105QDG1 ZL30106QDG1 ZL30107GGG2 ZL30109QDG1 ZL30111QDG1 ZL30116GGG2V2 ZL30117GGG2 ZL30119GGG2 ZL30120GGG2 ZL30121GGG2V2 ZL30122GGG2 ZL30123GGG2 ZL30130GGG2 ZL30131GGG2 ZL30132GGG2 ZL30136GGG2 ZL30138GGG2 ZL30142GGG2 ZL30143GGG2 ZL30145GGG2 ZL30146GGG2 ZL30150GGG2 ZL30152GGG2 ZL30153GGG2 ZL30154GGG2 ZL30155GGG2 ZL30156GGG2 ZL30157GGG2 ZL30158GGG2 ZL30159GGG2 ZL30160GGG2 ZL30160-GGG2-WH ZL30161GD ZL30161GDG2 ZL30162 ZL30162GDG2 ZL30163GDG2 ZL30163-GDG2-WE ZL30164GDG2 ZL30164GDG2Q036 ZL30164GDG2Q03M ZL30164-GDG2-WE

JAON-24EPKL576 - CCB 3970 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MSCC products available in various packages at ASEM assembly site. ZL30165GD ZL30165GDG2 ZL30166GD ZL30166GDG2 ZL30167GDG2 ZL30167-GDG2-WE ZL30168GDG2 ZL30168-GDG2-WD ZL30230GGG2 ZL30236GGG2 ZL30237GGG2 ZL30250LDF1 ZL30250LDG1 ZL30252LDF1 ZL30252LDG1 ZL30260LDF1 ZL30260LDG1 ZL30262LDF1 ZL30262LDG1 ZL30264LDF1 ZL30264LDG1 ZL30266LDF1 ZL30266LDG1 ZL30310GKG2 ZL30312GKG2 ZL30314GKG2 ZL30316GKG2 ZL30320GKG2 ZL30321GGG2 ZL30321GKG2 ZL30342GGG2 ZL30343GGG2 ZL30347GGG2 ZL30361GD ZL30361GDG2 ZL30362GD ZL30362GDG2 ZL30363GDG2 ZL30363GDG2Q03H ZL30363-GDG2-WE ZL30364GDG2 ZL30364GDG20042 ZL30364-GDG2-WE ZL30365GD ZL30365GDG2 ZL30367GDG2 ZL30367-GDG2-WE ZL38004GGG2 ZL38004QCG1

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ZL38005QCG1	
ZL38012LDF1	
ZL38012LDG1	
ZL38015QCG1	
ZL38040LDF1	
ZL38040LDG1	
ZL38042LDF1	
ZL38042LDG1	
ZL38050LDF1	
ZL38050LDG1	
ZL38051LDF1	
ZL38051LDG1	
ZL38052LDF1	
ZL38052LDG1	
ZL38060LDF1	
ZL38060LDG1	
ZL38062LDF1	
ZL38062LDG1	
ZL38063LDF1	
ZL38063LDG1	
ZL38065QCG1	
ZL38067LDF1	
ZL38067LDG1	
ZL38080LDF1	
ZL38080LDG1	
ZL38090LDF1	
ZL38090LDG1	
ZL38AMBLDF1	
ZL38AMBLDG1	
ZL40200LDF1	
ZL40200LDG1	
ZL40201LDF1	
ZL40201LDG1	
ZL40202LDF1	
ZL40202LDG1	
ZL40203LDF1	
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ZL40207LDF1	
ZL40207LDG1	
ZL40208LDF1	
ZL40208LDG1	
ZL40209LDF1	
ZL40209LDG1	

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ZL40250LDG1
ZL40252LDF1
ZL40252LDG1
ZL40260LDF1
ZL40260LDG1
ZL40260QGF1
ZL40260QGG1
ZL50232QCG1
ZL50233QCG1
ZL50234QCG1
ZL50235QCG1
ZL79124GDG2
ZL792388GDG2
ZL792588GDG2
ZL80018GGG2
ZL80020GDG2
ZL80025GGG2
ZL80026LDF1
ZL80026LDG1
ZL80027LDF1
ZL80027LDG1
ZL80143GGG2
ZL88103LDF1
ZL88103LDG1
ZL88105LDF1
ZL88105LDG1
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ZL88107LDG1
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